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Kenji [JP/JP]; 866-3, Ohmachi, Saijo-shi, Ehime 793-0030 (JP). OCHI, Hiroshi [JP/JP]; 454-15, Hinokuchi, Saijo-shi, Ehime 793-0043 (JP).

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(74) Agent: MORIMOTO, Yoshihiro; All Nippon Airways(Nishi-Hommachi)Bldg., 4th Floor, 10-10, Nishi-Hommachi 1-chome, Nishi-ku, Osaka-shi, Osaka 550-0005 (JP).

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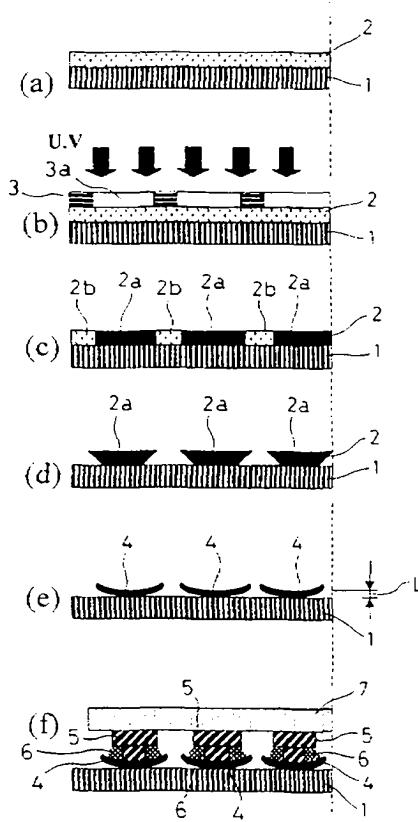
(71) Applicant (for all designated States except US): MAT-SUSHITA ELECTRIC INDUSTRIAL CO., LTD. [JP/JP]; 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501 (JP).

(72) Inventors: and

(75) Inventors/Applicants (for US only): MORIMOTO,

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(54) Title: FLIP CHIP PACKAGE, CIRCUIT BOARD THEREOF AND PACKAGING METHOD THEREOF



(57) **Abstract:** According to the present invention, when a semiconductor element (7) having protruding electrodes (5) formed thereon is connected to a circuit board (1) via conductive resin (6), stable connection is made even when an electrode pitch is small on the semiconductor element (7). On semiconductor element package regions on the circuit board (1), a paste electrode material (2) containing photopolymerizable materials is printed to form a film having a prescribed thickness, and this electrode material film (2) is baked after exposure and development thereof so as to obtain circuit electrodes (4) having edges warped in a direction of going apart from the circuit board (1) surface. Then, the protruding electrodes (5) and the concave surfaces of the circuit electrodes (4) are brought in abutment with each other and connected via the conductive resin (6) which surrounds the abutments between the respective electrodes and is held on the concave surfaces of the circuit electrodes (4). With this arrangement, the concave surfaces of the circuit electrodes (4) act as saucers and prevent the conductive resin (6) from being squeezed out, thereby eliminating possible occurrence of short circuits.

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A. CLASSIFICATION OF SUBJECT MATTER
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B. FIELDS SEARCHED

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 IPC 7 H05K H01L

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

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C. DOCUMENTS CONSIDERED TO BE RELEVANT

| Category | Citation of document, with indication, where appropriate, of the relevant passages | Relevant to claim No. |
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Name and mailing address of the ISA

European Patent Office, P.B. 5818 Patentlaan 2
NL - 2280 HV Rijswijk
Tel. (+31-70) 340-2040, Tx. 31 651 epo nl,
Fax: (+31-70) 340-3016

Authorized officer

Mes, L

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C.(Continuation) DOCUMENTS CONSIDERED TO BE RELEVANT

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